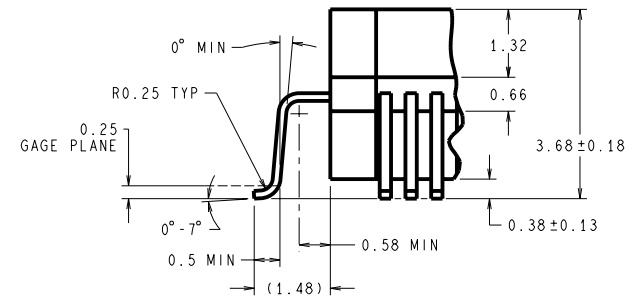
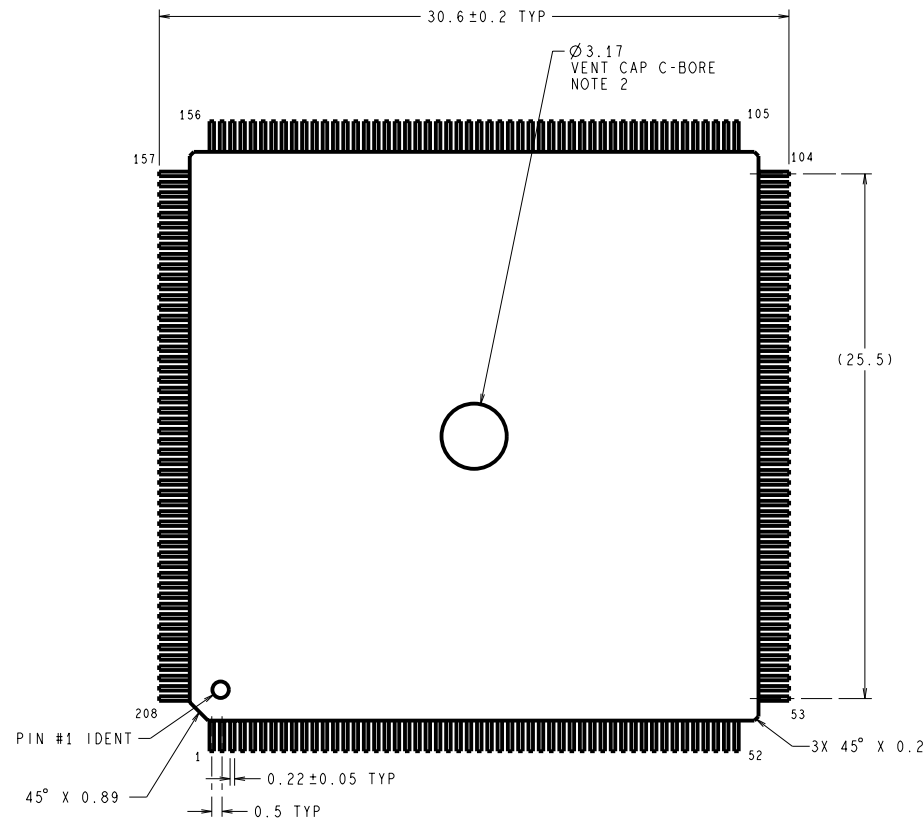
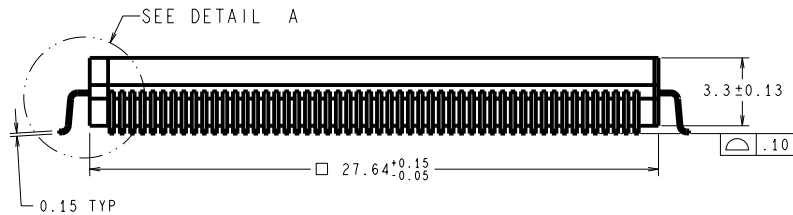


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
C	REVISE AND REDRAW PER NEW STANDARD.	11188	12/12/95	DEG/



DETAIL A
TYP, SCALE: 15X
NOTE 2



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

- STANDARD LEAD FINISH: 5.08 MICROMETERS MINIMUM SOLDER PLATING (85/15) THICKNESS.
- THE LEADS CAN BE FORMED FOR CAVITY UP OR DOWN:
-THE VENT CAP WILL BE ON THE TOP FOR CAVITY UP (SHOWN)
-THE VENT CAP WILL BE ON THE BOTTOM FOR CAVITY DOWN
- REFERENCE: OLIN DRAWING 04-208-YH-003, REV C, DATED MAY/92

APPROVALS		DATE	National Semiconductor			
DRAWN	<i>D. E. Grady</i>	12/12/95	2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DFTG. CHK.			MQAD, 28 X 28 X 3.3mm, 208 LEAD			
ENGR. CHK.						
		SCALE	SIZE	DRAWING NUMBER	REV	
		N/A	C	MKT-AUW208A	C	
DO NOT SCALE DRAWING						SHEET 1 of 1